KST2607

N&P-Channel complementary Power MOSFET

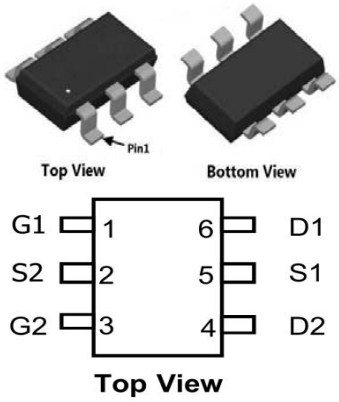
General Description

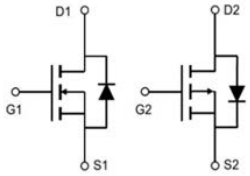
The KST2607 uses advanced technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.

Product Summary

	V_{DS} (V)	$R_{DS(on)}$ (mΩ)	I_D (A)
N-ch	20	28 at V_{GS} = 4.5V	7.0
		37 at V_{GS} = 2.5 V	5.6
P-ch	-20	40 at V_{GS} = -4.5 V	-6.8
		52 at V_{GS} = -2.5V	-5.2

SOT23-6 Pin Configuration





Features

- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Applications

- H-bridge
- Inverters

Absolute Maximum Ratings **Tc=25℃ unless otherwise noted**

Symbol	Parameter	N-ch Rating	P-ch Rating	Units
V_{DS}	Drain-Source Voltage	20	-20	V
V_{GS}	Gate-Source Voltage	±12	±12	V
I_D	Drain Current – Continuous (T_C=25℃)	7.0	-6.8	A
	Drain Current – Continuous (T_C=100℃)	4.0	-3.8	A
I_{DM}	Drain Current – Pulsed[1]	21	-19	A
P_D	Power Dissipation (T_C=25℃)	1.55		W
	Power Dissipation (T_C=100℃)	0.07		W/℃
T_{STG}	Storage Temperature Range	-55 to 150		℃
T_J	Operating Junction Temperature Range	-55 to 150		℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.5	℃/W

N-Channel Electrical Characteristics (TJ=25 ℃, unless otherwisenoted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	20	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=20V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=20V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±12V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=4.5V , I_D=4.0A	---	28	33	mΩ
		V_{GS}=2.5V , I_D=3.0A	---	37	44	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	0.7	1.0	1.5	V
gfs	Forward Transconductance	V_{DS}=10V , I_S=1.5A	---	20	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[2,3]	V_{DD}=10V , V_{GS}=5V , I_D=3.0A	---	5.7	---	nC
Q_{gs}	Gate-Source Charge[2,3]		---	0.7	---	
Q_{gd}	Gate-Drain Charge[2,3]		---	0.8	---	
$T_{d(on)}$	Turn-On Delay Time[2,3]	V_{DS}=10V, R_L=2.5Ω V_{GS}=5V,R_G=3Ω	---	4.8	---	ns
T_r	Rise Time[2,3]		---	1.8	---	
$T_{d(off)}$	Turn-Off Delay Time[2,3]		---	16	---	
T_f	Fall Time[2,3]		---	10	---	
C_{iss}	Input Capacitance	V_{DS}=10V , V_{GS}=0V , F=1MHz	---	480	---	pF
C_{oss}	Output Capacitance		---	95	---	
C_{rss}	Reverse Transfer Capacitance		---	43	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	5	A
I_{SM}	Pulsed Source Current		---	---	14	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1.0	V

N-Channel Typical Electrical and Thermal Characteristics (Curves)

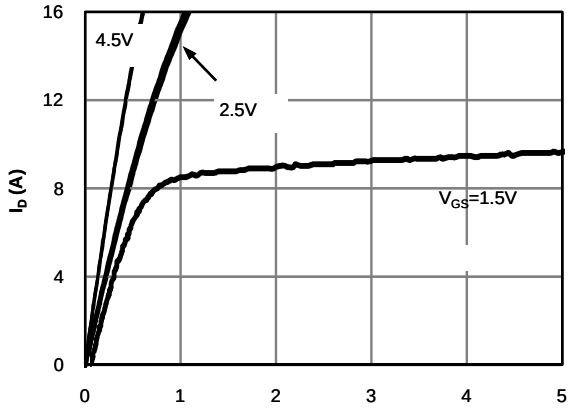


Fig1: On-Region Characteristics

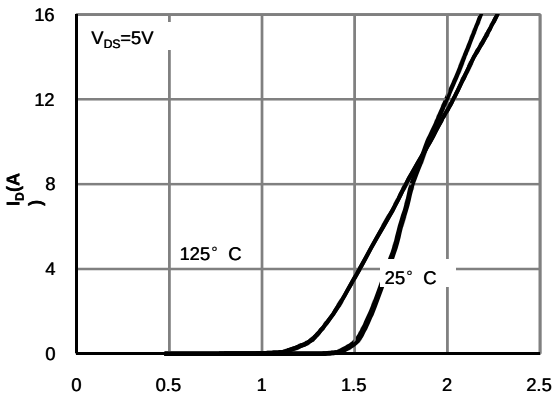


Figure2:Transfer Characteristics

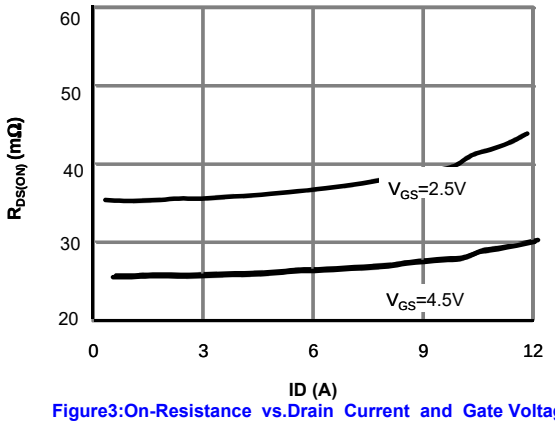


Figure3:On-Resistance vs.Drain Current and Gate Voltage

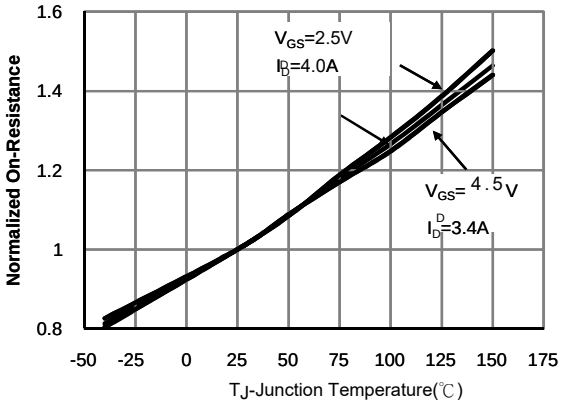


Fig. 4 Drain-Source On-Resistance

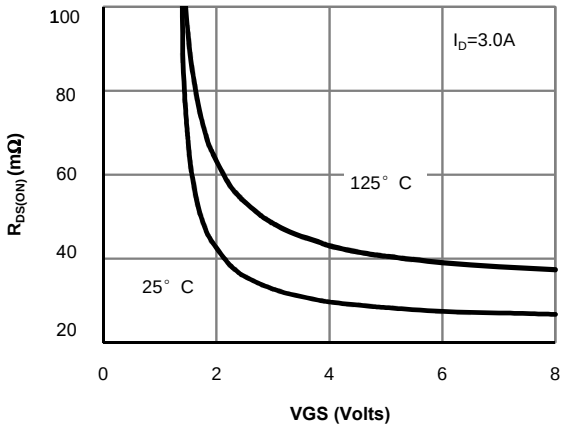


Figure 5: On-Resistance vs. Gate-Source Voltage

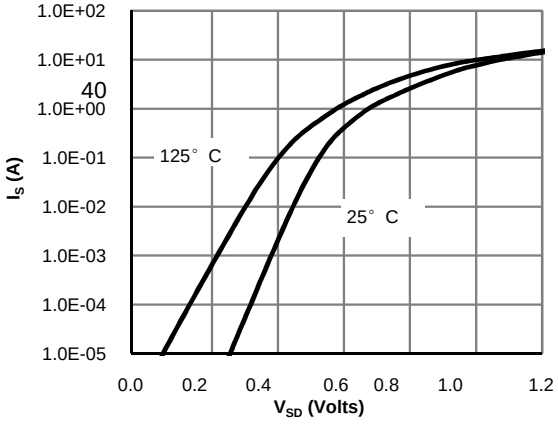


Figure 6: Body-Diode Characteristics

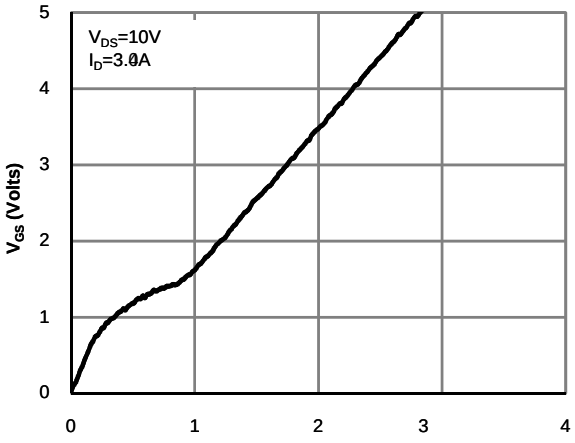


Figure 7: Gate-Charge Characteristics

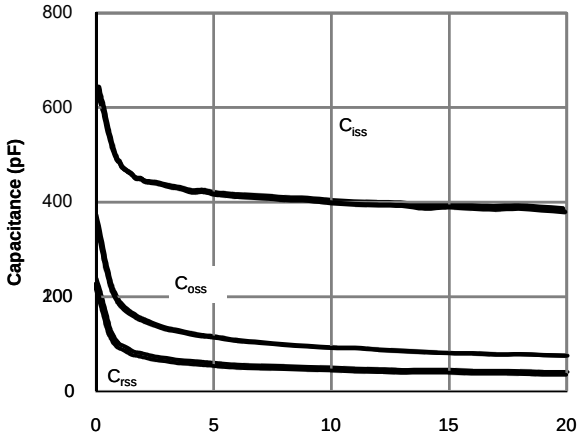


Figure 8: Capacitance Characteristics

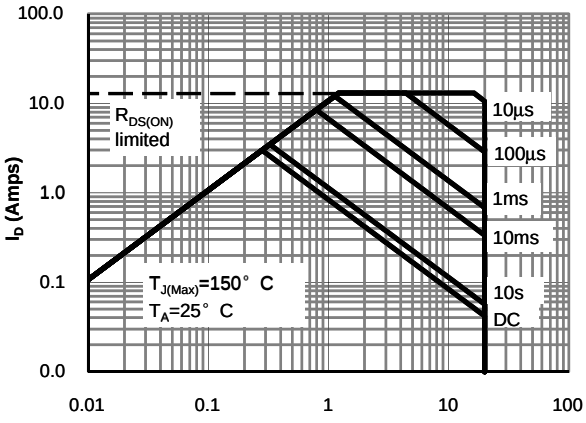


Figure 9: Safe Operation Area

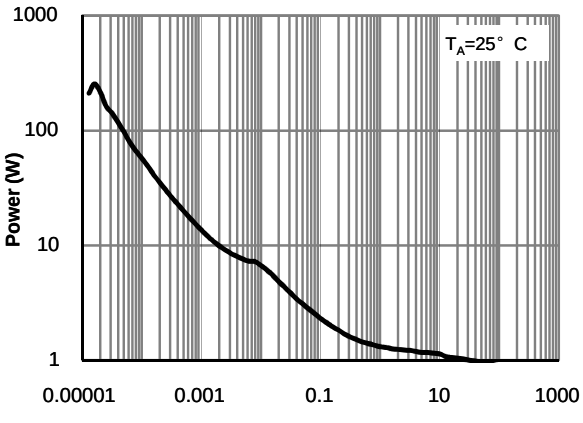


Figure 10: Single Pulse Power Rating Junction-to-Ambient

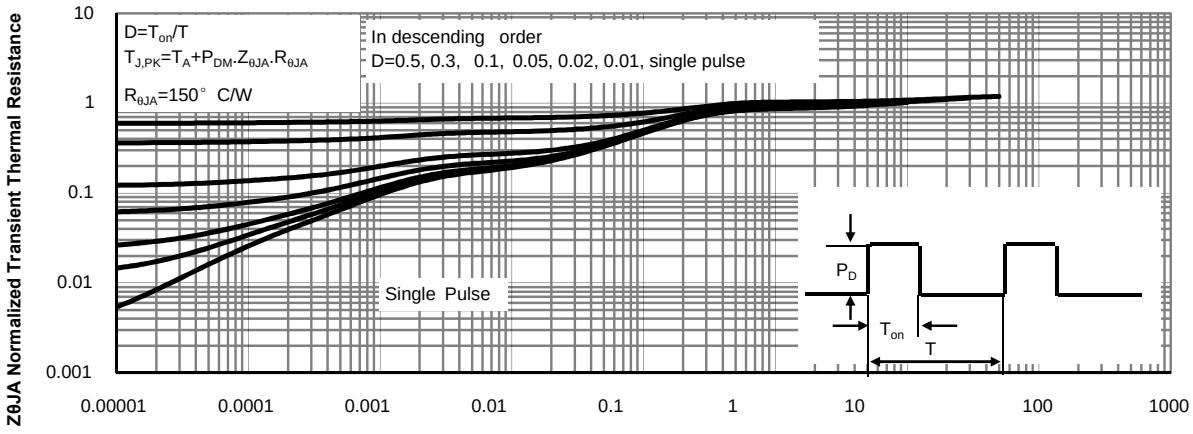


Figure 11: Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics (T_J=25 ℃, unless otherwisenoted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-20	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-20V , V_{GS}=0V , T_J=25℃	---	---	-1	uA
		V_{DS}=-20V , V_{GS}=0V , T_J=125℃	---	---	-10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±12V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-4.5V , I_D=-3.0A	---	40	48	mΩ
		V_{GS}=-2.5V , I_D=-2.0A	---	52	62	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	-0.7	-1.0	-1.5	V
gfs	Forward Transconductance	V_{DS}=-5V , I_S=-2A	---	20	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge	V_{DS}=-10V , V_{GS}=-4.5V , I_D=-2.8A	---	8.5	---	nC
Q_{gs}	Gate-Source Charge		---	3.2	---	
Q_{gd}	Gate-Drain Charge		---	2.0	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DS}=-10V, R_L=5.8Ω V_{GS}=-4.5V,R_G=3.3Ω	---	9.5	---	ns
T_r	Rise Time		---	3.9	---	
$T_{d(off)}$	Turn-Off Delay Time		---	13	---	
T_f	Fall Time		---	3.4	---	
C_{iss}	Input Capacitance	V_{DS}=-10V , V_{GS}=0V , F=1MHz	---	582	---	pF
C_{oss}	Output Capacitance		---	106	---	
C_{rss}	Reverse Transfer Capacitance		---	78	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	-6	A
I_{SM}	Pulsed Source Current		---	---	-17	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=-1A , T_J=25℃	---	---	-1.0	V

Note :

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E_{AS} condition: Tj=25℃,V_{DD}=-15V,V_G=-10V,L=0.5mH,Rg=25Ω,I_{AS}=-26A

P-Channel Typical Electrical and Thermal Characteristics (Curves)

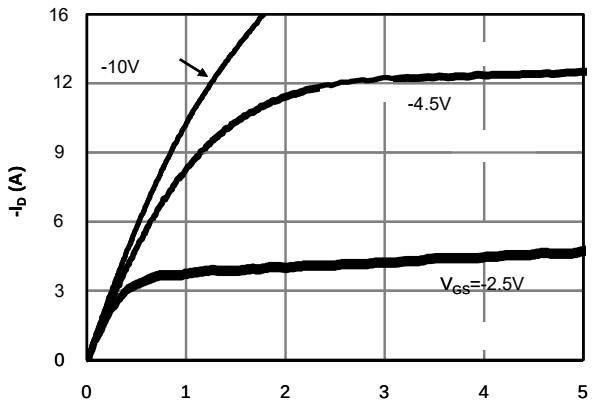


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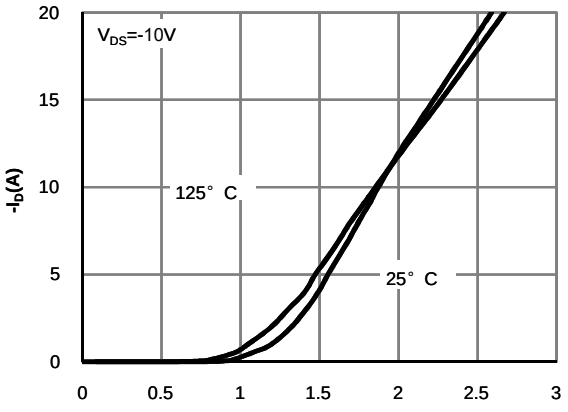


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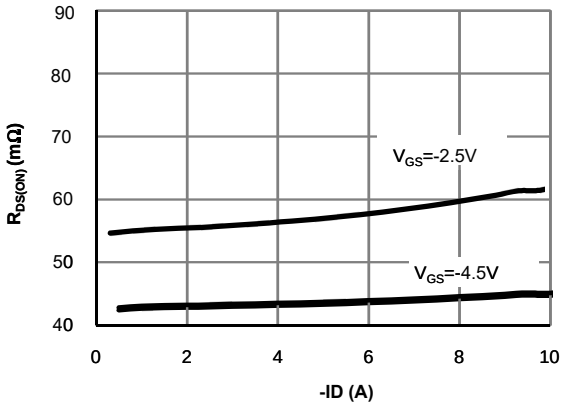


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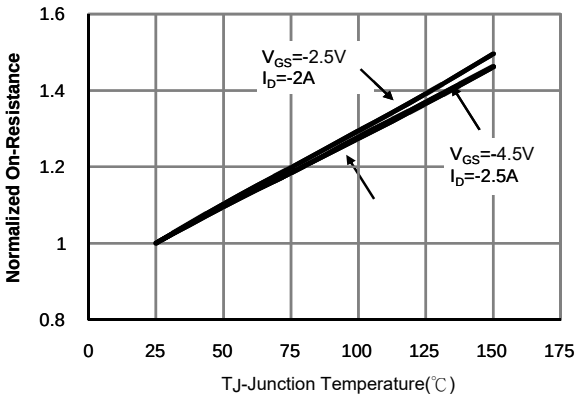


Fig. 4 Drain-Source On-Resistance

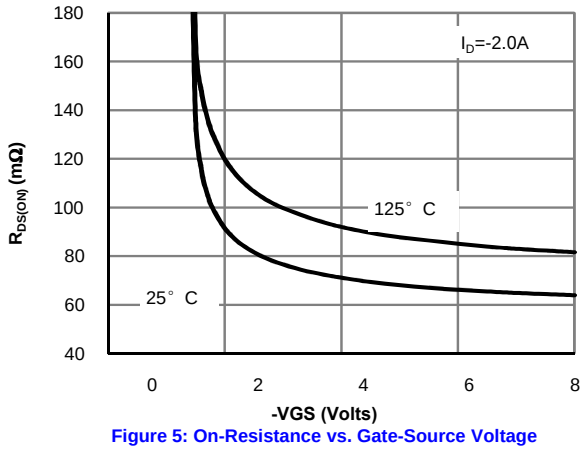


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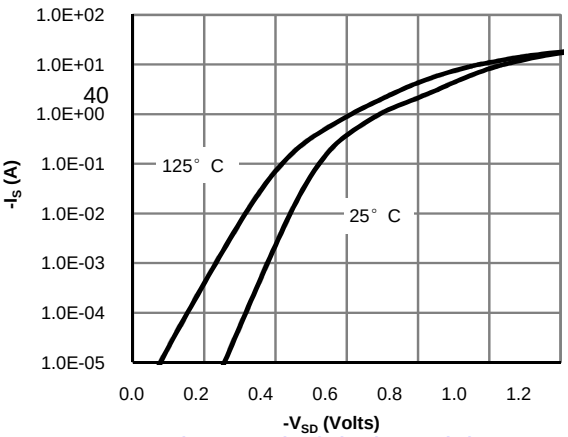


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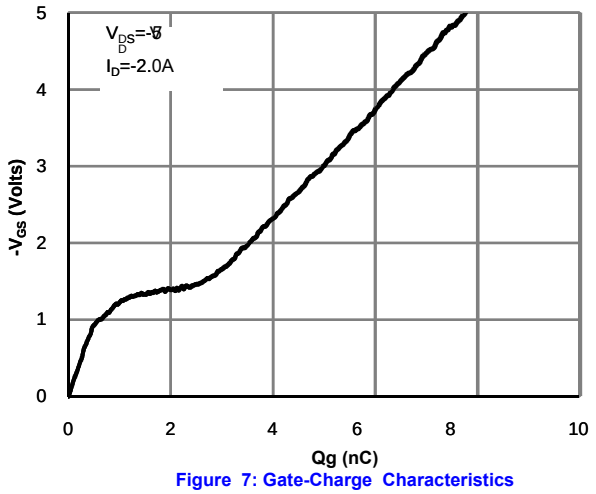


Figure 7: Gate-Charge Characteristics

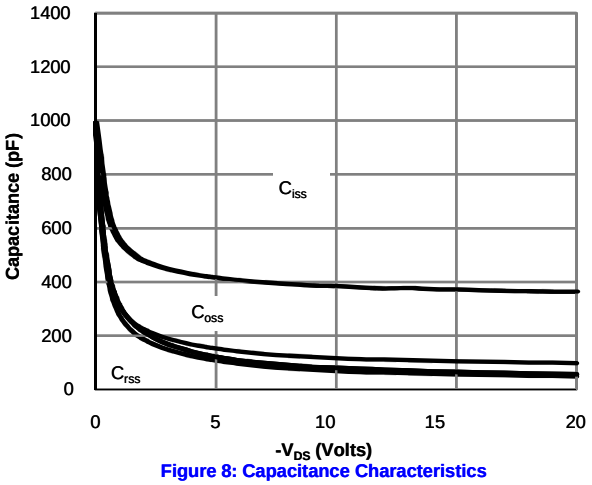


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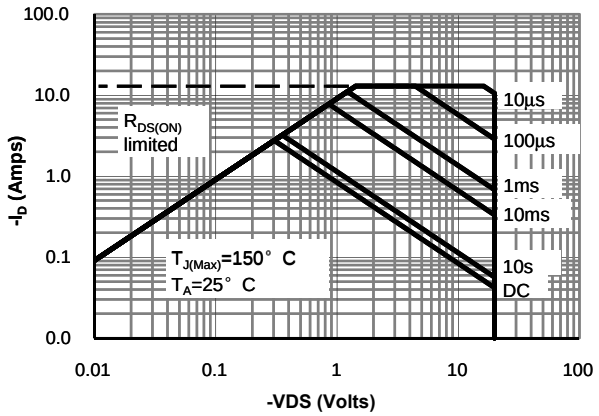


Figure9:Maximum Forward Biased Safe Operating Area

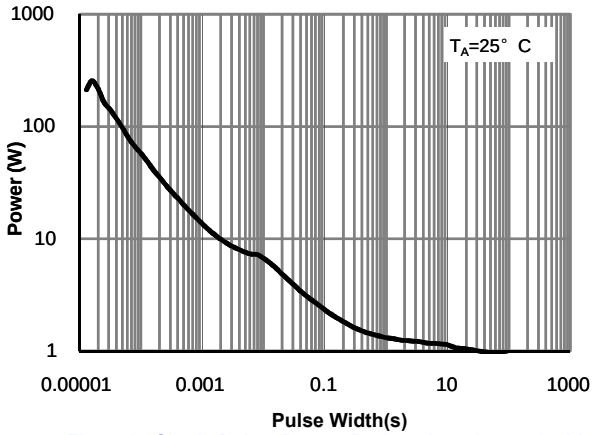


Figure10:Single Pulse Power Rating Junction-to Ambient

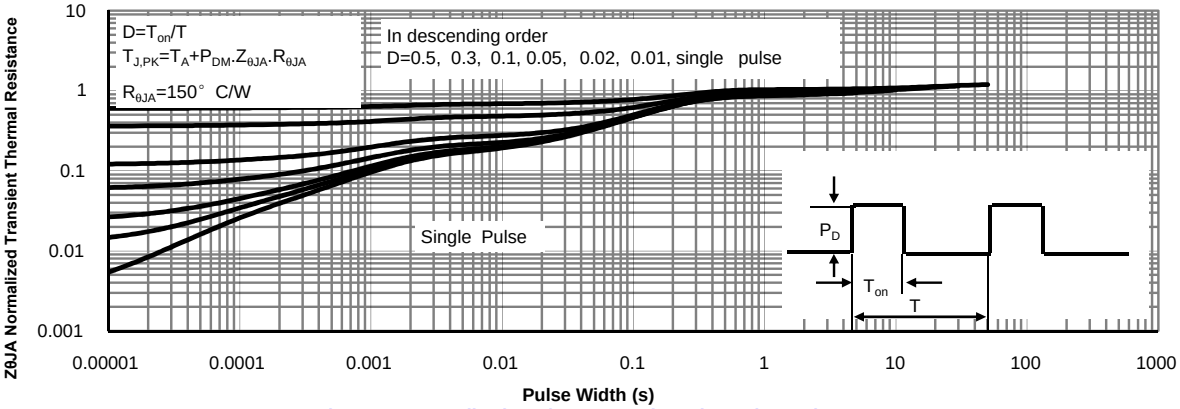


Figure 11: Normalized Maximum Transient Thermal Impedance

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